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|--------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------|
| <b>Title of Change:</b>        | Qualification of ROHM SiC 20A as alternate wafer source                                                                                                       |
| <b>Effective date:</b>         | 25 Jul 2022                                                                                                                                                   |
| <b>Contact information:</b>    | Contact your local onsemi Sales Office or <a href="mailto:Way-Shan.Yong@onsemi.com">Way-Shan.Yong@onsemi.com</a>                                              |
| <b>Type of notification:</b>   | This Product Bulletin is for notification purposes only.<br>onsemi will proceed with implementation of this change upon publication of this Product Bulletin. |
| <b>Change Category:</b>        | Wafer Fab Change                                                                                                                                              |
| <b>Change Sub-Category(s):</b> | Material Change                                                                                                                                               |

**Sites Affected:**

**onsemi Sites**

None

**External Foundry/Subcon Sites**

ROHM Japan

**Description and Purpose:**

This Product Bulletin announces alternate parts using ROHM Japan SiC wafer supplier to provide additional ordering options for our customers.

PIM module production for current OPNs and new OPNs is onsemi Shenzhen, China.

Both parts can be used interchangeably, and customers can determine which OPN they want to place orders on. The product is qualified to industrial requirements.

|           | Existing Parts       | Alternate Parts     |
|-----------|----------------------|---------------------|
| SiC wafer | onsemi Bucheon Korea | ROHM Japan          |
| OPN       | Existing BK OPNs     | New ROHM Japan OPNs |

There is no product marking change to existing OPN as a result of this change. New OPNs were created for parts using ROHM Japan dice.

**QV DEVICE NAME: S6304(Rohm SiC Diode 6inch)**

**PACKAGE: Q2x Module**

| Test   | Specification | Condition                       | Interval | Results |
|--------|---------------|---------------------------------|----------|---------|
| HTRB   | JESD22-A108   | Tj=175°C, 100% max rated V      | 1008 hrs | 0/33    |
| H3TRB  | JESD22-A101   | Ta=85°C, 85%RH, 80% max rated V | 1008 hrs | 0/33    |
| H3TRBx | JESD22-A101   | Ta=85°C, 85%RH, 100V            | 1008 hrs | 0/28    |
| HTSL   | JESD22-A103   | Ta= 150°C                       | 1008 hrs | 0/33    |
| THU    | JESD22-A101   | Ta=85°C, 85%RH                  | 1008 hrs | 0/33    |

**List of Affected Standard Parts:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

| Existing Parts      | Alternate Parts       |
|---------------------|-----------------------|
| NXH600B100H4Q2F2PG  | NXH600B100H4Q2F2PG-R  |
| NXH600B100H4Q2F2SG  | NXH600B100H4Q2F2SG-R  |
| NXH350N100H4Q2F2P1G | NXH350N100H4Q2F2P1G-R |
| NXH350N100H4Q2F2S1G | NXH350N100H4Q2F2S1G-R |
| NXH400N100H4Q2F2SG  | NXH400N100H4Q2F2SG-R  |
| SNXH200B100H4Q1SG   | SNXH200B100H4Q1SG-R   |
| NXH200B100H4F2SG    | NXH200B100H4F2SG-R    |